

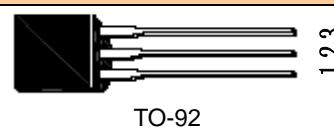
## 1. Description

Designed for use in solid state relays, MPU interface, TTL logic and any other light industrial or consumer application. Supplied in an inexpensive TO-92 package which is readily adaptable for use in automatic insertion equipment. Sensitive Gate Triggering In Four Trigger Modes for all possible Combinations of Trigger Sources, and Especially for Circuits that Source Gate Drives

## 2. Features

- Blocking voltage to 600V
- On-state RMS current to 1.0 A
- Sensitive Gate Triggering in Four Trigger Modes (Quadrants) for all possible Combinations of Trigger Sources, and especially for Circuits that Source Gate Drives
- All Diffused and Glassivated Junctions for Maximum Uniformity of Parameters and Reliability
- Low cost package.

## 3. Pinning information

PIN		Simplified outline	Symbol
1	main terminal 1(T1)		
2	Gate(G)		
3	main terminal 2(T2)		
tab	main terminal		

## 4. Quick reference data

SYMBOL	PARAMETER	MAX	UNIT
$V_{DRM}$ & $V_{RRM}$	Repetitive peak off-state voltages	600	V
$I_T$ (RMS)	RMS on-state current	1.0	A
$I_{TSM}$	Non-repetitive peak on-state current	10	A

## 5. Thermal characteristics

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Thermal Resistance, Junction to Case	in free air	-	-	75	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	in free air	-	-	200	°C/W
$T_L$	Maximum Lead Temperature for Soldering Purposes for 10 Seconds	in free air	-	-	260	°C

## 6. Limiting value

Limiting values in accordance with the Maximum System(IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
$V_{DRM}$ & $V_{RRM}$	Repetitive peak off-state voltages		-	-	600	V
$I_{T(RMS)}$	RMS on-state current	Full Cycle Sine Wave 50 to 60 Hz ( $T_C = +50^\circ\text{C}$ )	-	-	1.0	A
$I_{TSM}$	Non-repetitive peak on-state current	One Full Cycle, Sine Wave 60 Hz ( $T_C = 110^\circ\text{C}$ )	-	-	10	A
$I^2t$	$I^2t$ for fusing	$t = 8.3 \text{ ms}$	-	-	0.26	$\text{A}^2\text{s}$
$I_{GM}$	Peak gate current		-	-	1.0	A
$V_{GM}$	Peak gate voltage		-	-	5.0	V
$P_{GM}$	Peak gate power		-	-	5.0	W
$P_{G(AV)}$	Average gate power	over any 20 ms period	-	-	0.5	W
$T_{stg}$	Storage temperature		-40	-	150	$^\circ\text{C}$
$T_j$	Operating junction temperature		-40	-	110	$^\circ\text{C}$

## 7. Characteristics

$T_J = 25$  unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
<b>Static characteristics</b>						
$I_{GT}$	Gate trigger current	( $V_D = 12 \text{ Vdc}$ , $R_L = 100 \text{ Ohms}$ )				
		T2+ G+	-	3	5	mA
		T2+ G-	-	3	5	mA
		T2- G-	-	3	5	mA
		T2- G+	-	5	7	mA
$I_L$	Latching current	$V_D = 12 \text{ V}$ ; $I_{GT} = 0.1\text{A}$				
		T2+ G+	-	1.6	10	mA
		T2+ G-	-	10.5	20	mA
		T2- G-	-	1.5	15	mA
		T2- G+	-	2.5	15	mA
$I_H$	Holding current	$V_D = 12 \text{ V}$ ; Initiating Current = 200 mA, Gate Open	-	1.5	10	mA
$V_{GT}$	Gate trigger voltage	$V_D = 12 \text{ V}$ ; $I_T = 0.1\text{A}$				
		T2+ G+	-	0.66	2.0	V
		T2+ G-	-	0.77	2.0	V
		T2- G-	-	0.84	2.0	V
		T2- G+	-	0.88	2.5	V
$V_{GD}$	Off-state leakage Voltage	$V_D = 12 \text{ V}$ , $R_L = 100 \text{ Ohms}$ , $T_J = 110^\circ\text{C}$ ;All Four Quadrants	0.1	-	-	V
<b>Dynamic Characteristics</b>						
$dv/dt(c)$	Critical Rate-of-Rise of Commutation Voltage	$V_D = \text{Rated } V_{DRM}$ , $I_{TM} = .84 \text{ A}$ , Commutating $di/dt = .3 \text{ A/ms}$ , Gate Unenergized, $T_C = 50^\circ\text{C}$	-	5.0	-	$\text{V}/\mu\text{s}$
$dv/dt$	Critical Rate of Rise of Off-State Voltage	$V_D = \text{Rated } V_{DRM}$ , $T_C = 110^\circ\text{C}$ , Gate Open, Exponential Waveform	-	25	-	$\text{V}/\mu\text{s}$
$t_{gt}$	Gate controlled turn-on time	$V_D = \text{Rated } V_{DRM}$ , $I_{TM} = 1.0 \text{ A pk}$ , $I_G = 25 \text{ mA}$	-	2.0	-	$\mu\text{s}$

Vast

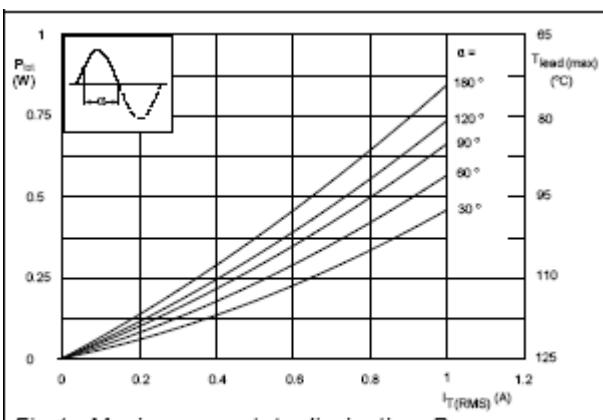


Fig.1. Maximum on-state dissipation,  $P_{oss}$ , versus rms on-state current,  $I_T(RMS)$ , where  $\alpha$  = conduction angle.

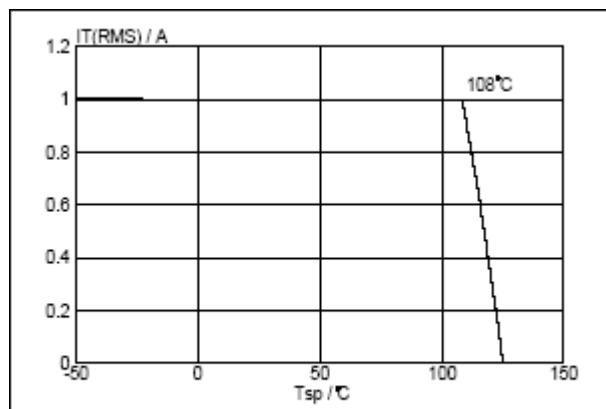


Fig.4. Maximum permissible rms current  $I_T(RMS)$  versus lead temperature  $T_{lead}$ .

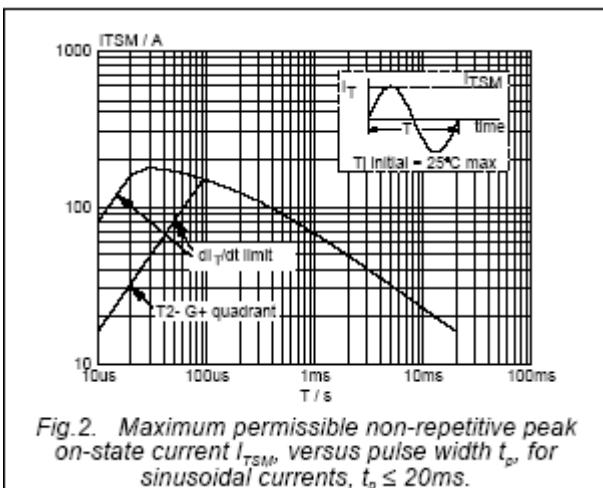


Fig.2. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus pulse width  $t_p$ , for sinusoidal currents,  $t_p \leq 20\text{ms}$ .

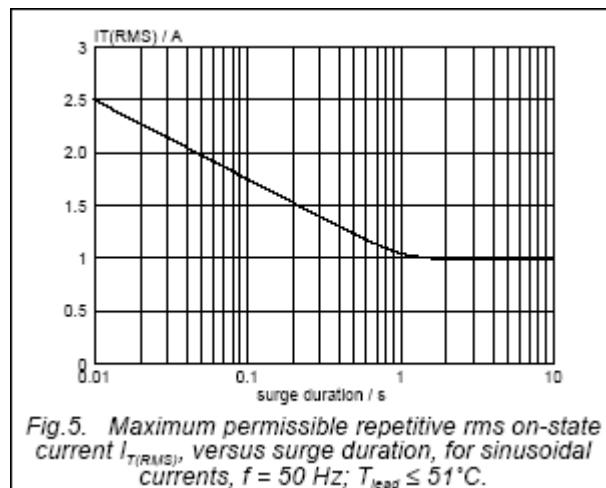


Fig.5. Maximum permissible repetitive rms on-state current  $I_{T(RMS)}$ , versus surge duration, for sinusoidal currents,  $f = 50\text{ Hz}$ ;  $T_{lead} \leq 51^\circ\text{C}$ .

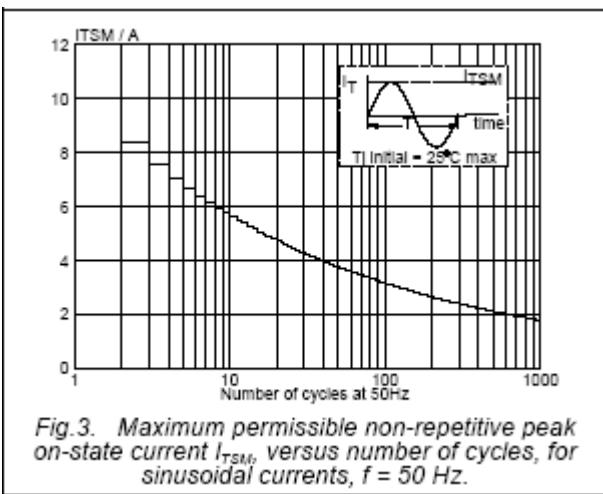


Fig.3. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus number of cycles, for sinusoidal currents,  $f = 50\text{ Hz}$ .

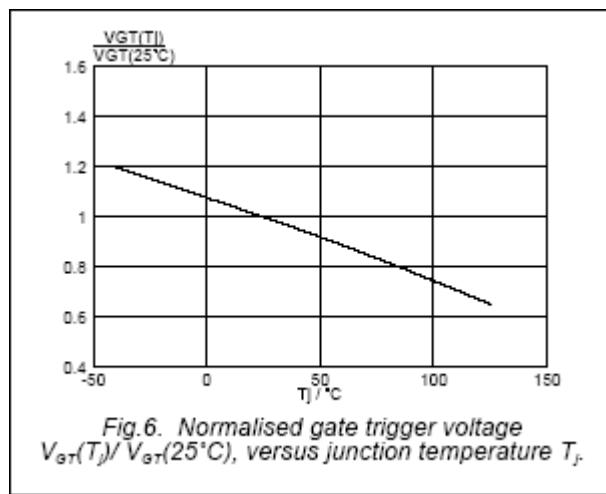


Fig.6. Normalised gate trigger voltage  $V_{GT}(T_j)/V_{GT}(25^\circ\text{C})$ , versus junction temperature  $T_j$ .

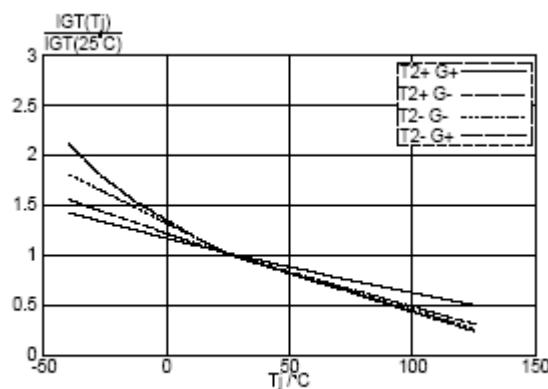


Fig.7. Normalised gate trigger current  $I_{GT}(T_j)/I_{GT}(25^\circ\text{C})$ , versus junction temperature  $T_j$ .

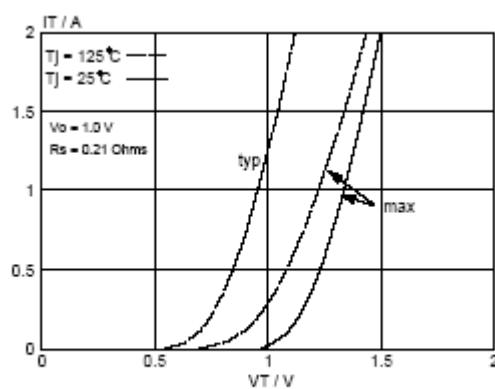


Fig.10. Typical and maximum on-state characteristic.

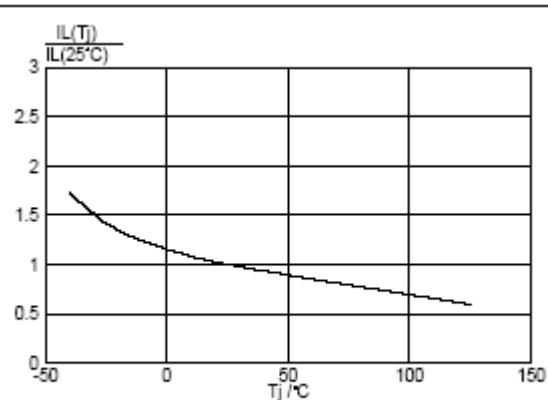


Fig.8. Normalised latching current  $I_L(T_j)/I_L(25^\circ\text{C})$ , versus junction temperature  $T_j$ .

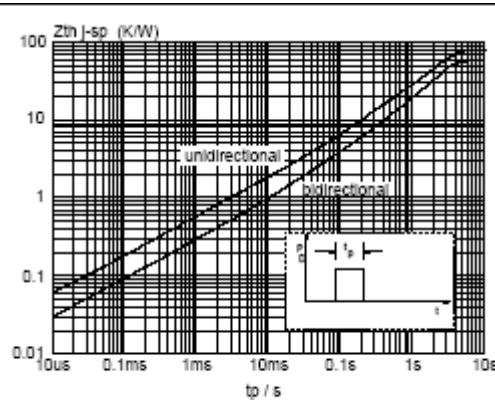


Fig.11. Transient thermal impedance  $Z_{th,I-sp}$  versus pulse width  $t_p$ .

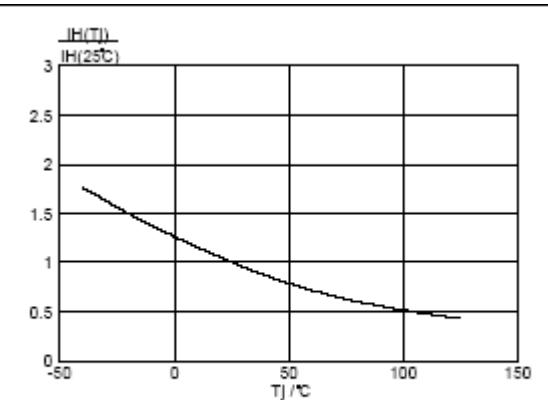


Fig.9. Normalised holding current  $I_H(T_j)/I_H(25^\circ\text{C})$ , versus junction temperature  $T_j$ .

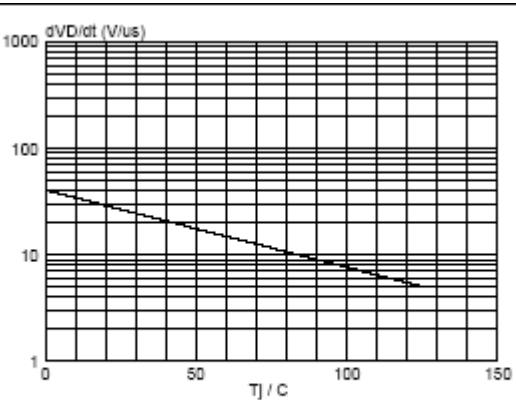
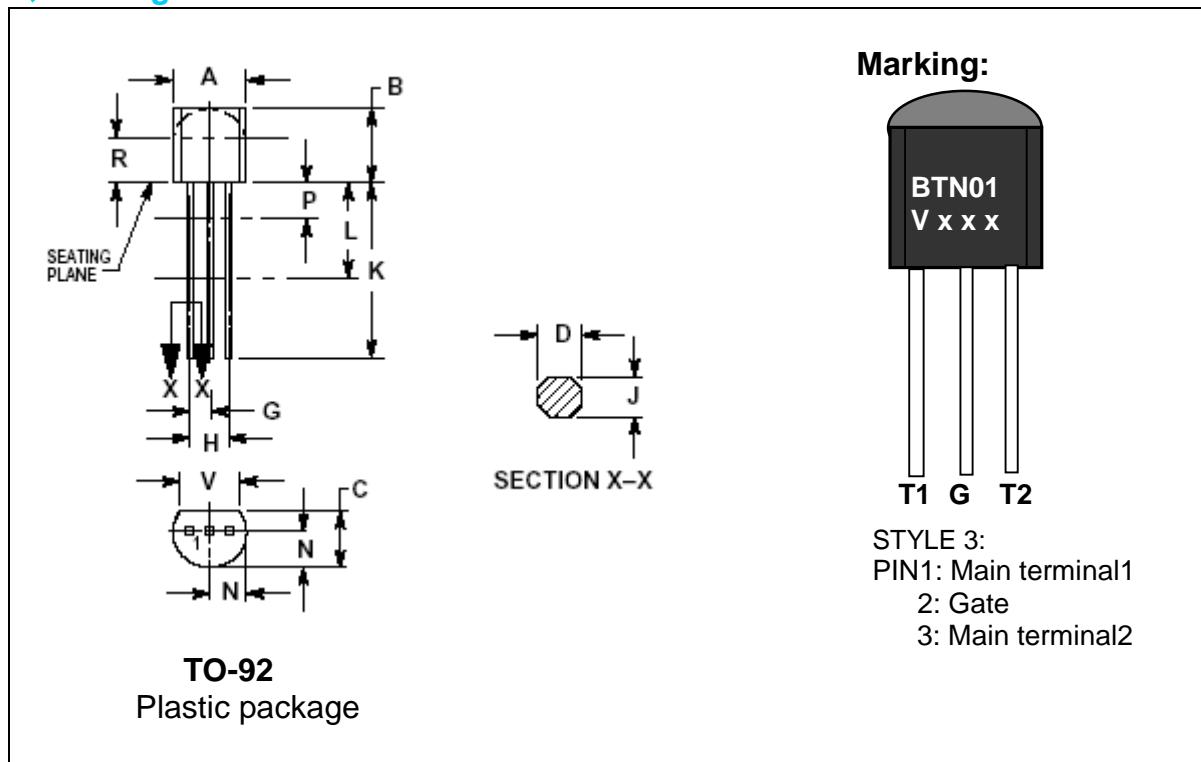


Fig.12. Typical, critical rate of rise of off-state voltage,  $dV_D/dt$  versus junction temperature  $T_j$ .

## 8. Package outline



DIM	Inches		Milimeters		DIM	Inches		Milimeters	
	Min	Max	Min	Max		Min	Max	Min	Max
A	0.175	0.205	4.45	5.20	K	0.500	-	12.70	-
B	0.170	0.210	4.32	5.33	L	0.250	-	6.35	-
C	0.140	0.144	3.50	3.60	N	0.080	0.105	2.04	2.66
D	0.016	0.021	0.407	0.533	P	-	0.100	-	2.54
H	0.045	0.055	2.42	2.66	R	0.115	-	2.93	-
G	0.095	0.105	1.27	2.41	V	0.135	-	3.43	-
J	0.015	0.020	0.39	0.50	-	-	-	-	-